

## High Efficiency, Synchronous Boost Converter with QC 2.0 Fast Charging Function

### Description

The HM5277 is highly-integrated switch-mode system power management devices for smart power bank application and regulated output voltage including 5V /9V /12V. Its low impedance power switch optimizes switch-mode operation efficiency, reduces MOS power consumption. The USB D+/D- data line makes the device protocol handshake to set suitable output voltage to do fast charging function.

The chip is compliant with QC 2.0 class A specifications with Max. output current up to 3A at 5V. Besides the converter includes two switch MOSFETs as synchronous boost converter. So no external Schottky diode is required and could get better efficiency near 92%.

Other features include built-in soft start, thermal shutdown protection, under-voltage lockout (UVLO), and short circuit protection function, which can shut off the device if output voltage reaches below 1.5V.

The HM5277 is available in a space-saving SOP-8 (Exposed Pad) package with an exposed pad.

### Features

- Input Voltage Range from 2.9V to 5.5V.
- Output Voltage Can be Set to 5V/9V/12V.
- Built-in Low  $R_{DS(ON)}$  Integrated Power MOSFET NMOS 39mΩ/PMOS 42mΩ
- 3.0A Output Current at 5V
- Fixed Switching Frequency 500KHz .
- ±2% Voltage Accuracy
- Power-Save Mode for Light-Load Efficiency.
- Short Circuit Current Fold-back Protection.
- Built-in Soft Start, Output Overvoltage Protection and Thermal Protection
- Supports USB DCP Shorting D+ Line to D- Line per USB Battery Charging Specification, Revision 1.2.
- Meets Chinese Telecommunication Industrial Standard YD/T 1591-2009
- Supports USB DCP applying 2.7V on D+ line and 2.7V on D- line.
- Supports USB DCP applying 1.2V on D+ and D- lines
- Automatic selection of D+/D- mode for an attached device
- Complaint with Apple® and Samsung devices
- SOP-8 (Exposed Pad) Pb-Free Package

### Applications

- Backup Battery Pack
- Mobile / Tablet Power
- Digital Cameras and Bluetooth Accessories
- USB Power Output Ports

### Pin Assignments

SP Package (SOP-8 Exposed Pad)

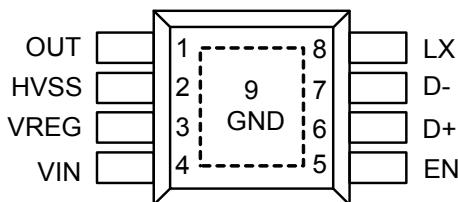
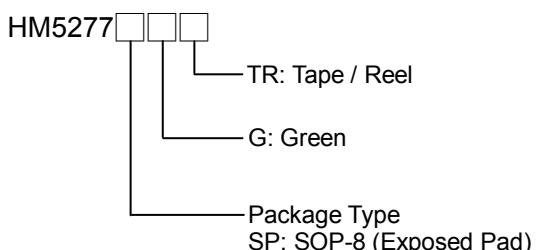


Figure 1. Pin Assignment of HM5277

### Ordering Information



## Typical Application Circuit

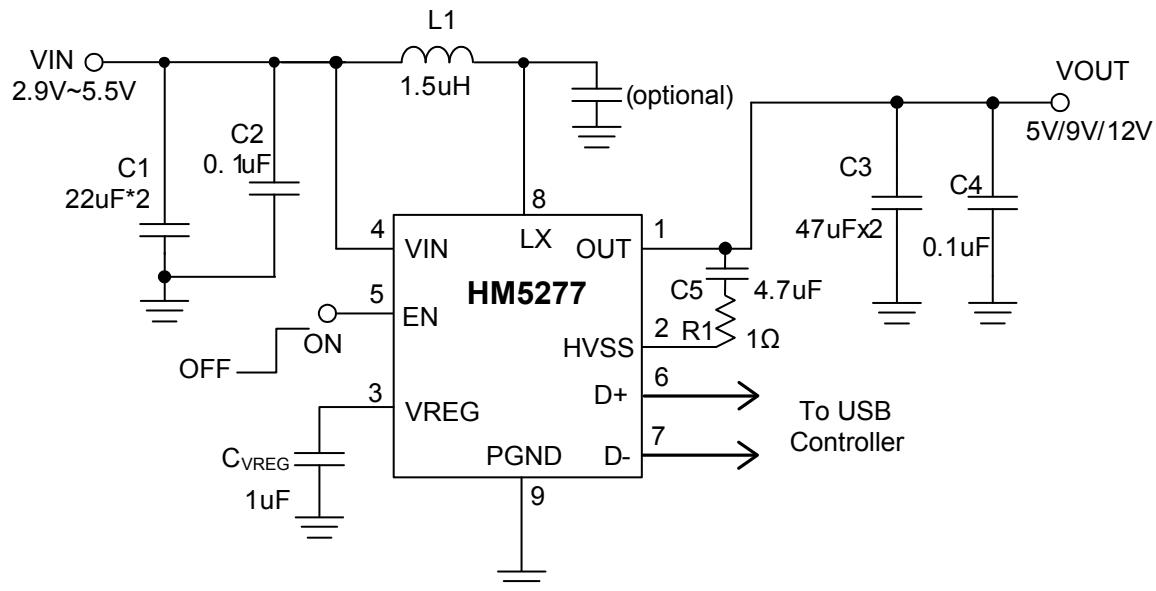


Figure 2. Typical Application Schematic

## Functional Pin Description

Pin Name	Pin No.	Pin Function
OUT	1	Output of the Synchronous Rectifier.
HVSS	2	PMOS Gate Drive Pin. A capacitance 4.7uF must be connected from this pin to OUT. It can gate drive to fully turn on the internal PMOS.
VREG	3	Regulation Voltage Pin. It must be bypassed with at least a 1μF capacitor to GND
VIN	4	Power Supply Input Pin.
EN	5	Logic Controlled Shutdown Input.
D+	6	USB D+ data line input
D-	7	USB D- data line input
LX	8	Power Switching Connection. Connect LX to the inductor and output rectifier.
GND	9	The thermal pad must be connected to the same potential as the GND pin on the printed circuit board.

## Block Diagram

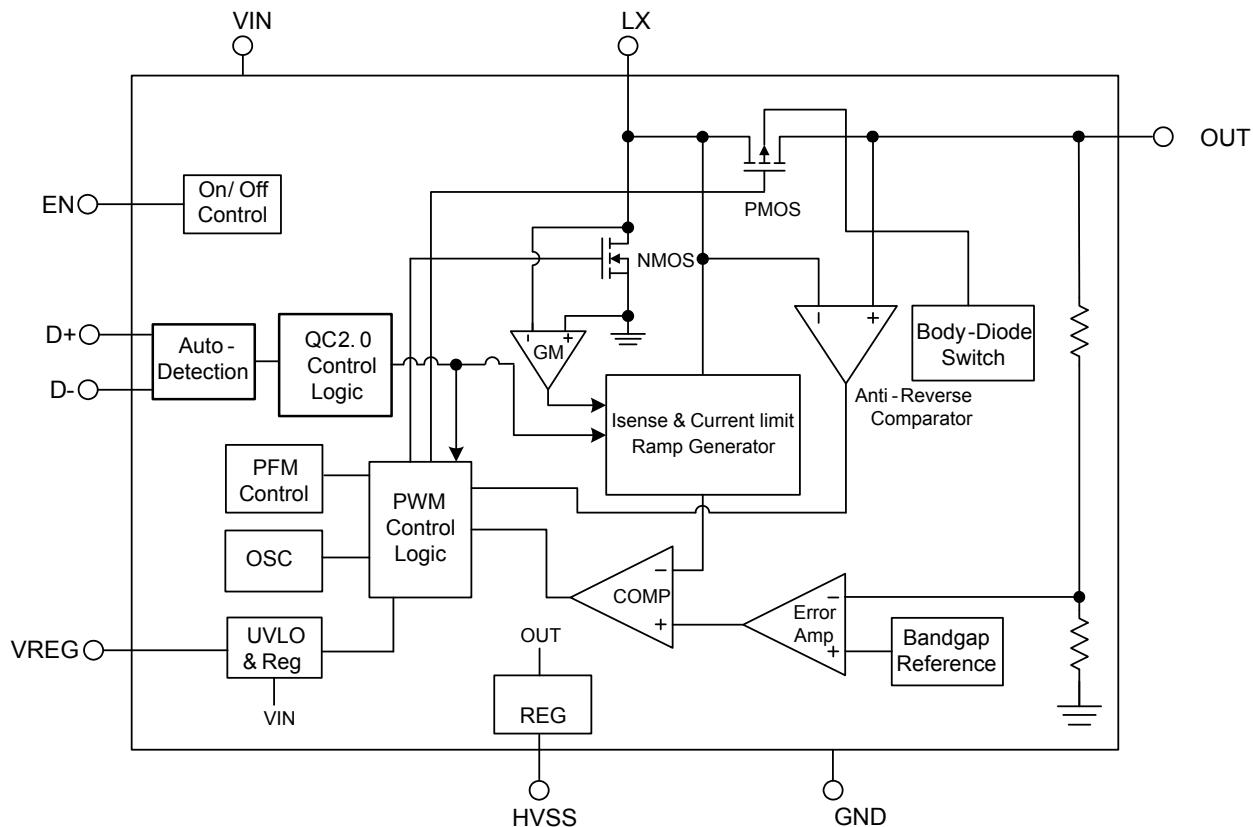


Figure 3. Block Diagram of HM5277

## Absolute Maximum Ratings

- Input Supply Voltage VIN ----- - 0.3V to + 6V
- Output Voltage V<sub>OUT</sub>----- - 0.3V to + 15V
- All Other Pins Voltage ----- - 0.3V to + 6V
- LX to GND ----- -0.3V to +18V
- Maximum Junction Temperature (T<sub>J</sub>)----- + 150°C
- Storage Temperature (T<sub>S</sub>)----- - 65°C to + 150°C
- Lead Temperature (Soldering, 10sec.) ----- +260°C
- Power Dissipation @T<sub>A</sub>=25°C, (P<sub>D</sub>)  
    SOP-8 (Exposed Pad)----- 2.08W
- Package Thermal Resistance, (θ<sub>JA</sub>):  
    SOP-8 (Exposed Pad)----- 60°C/W
- Package Thermal Resistance, (θ<sub>JC</sub>):  
    SOP-8 (Exposed Pad)----- 15°C/W

Note1 : Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device.

## Recommended Operating Conditions

- Input Supply Voltage (VIN)----- 2.9V ~ 5.5V
- OUT Operating Voltage (V<sub>OUT\_OPAT</sub>)----- 5V ~ 12V
- Operation Temperature Range (T<sub>OPR</sub>) ----- -40°C to +85°C

Note : Over operating free-air temperature range (unless otherwise noted)

## Electrical Characteristics

( $T_A=25^\circ\text{C}$  and the recommended supply voltage range, unless otherwise specified.)

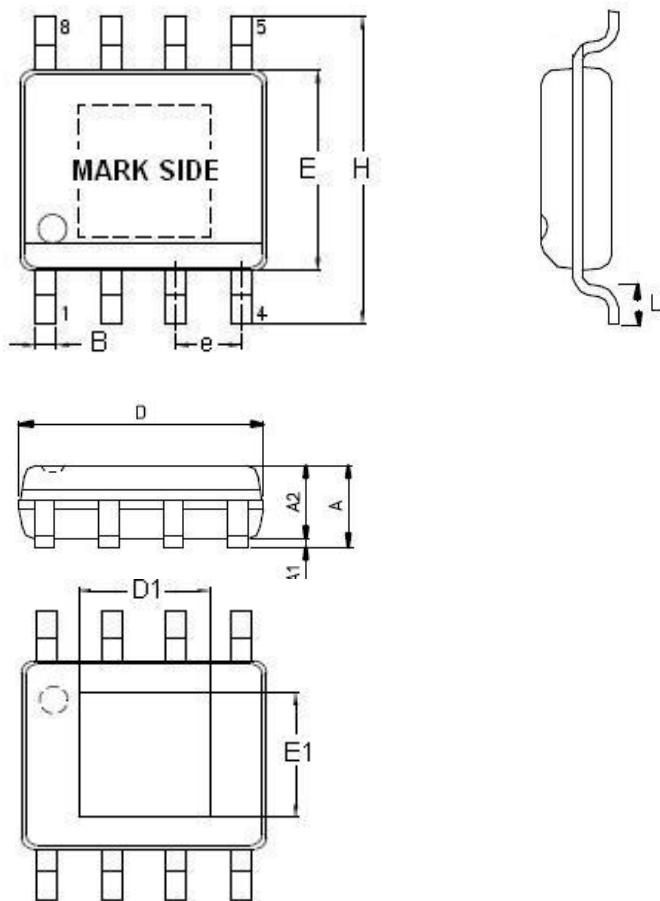
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
<b>Input Power</b>						
VIN Input Voltage Range	$V_{IN}$		2.9		5.5	V
Input UVLO Threshold	$V_{UVLO(VTH)}$	$V_{IN}$ Rising	2.5	2.7		V
Under Voltage Lockout Threshold Hysteresis	$V_{UVLO(HYS)}$	$V_{IN}$ Falling		250		mV
VIN Supply Current (Switching)		$V_{IN}=3.3\text{V}$ , Measure $V_{IN}$		TBD		$\mu\text{A}$
VIN Supply Current (No switching)				TBD		$\mu\text{A}$
Reference Voltage	$V_{REG}$			5		V
High-Side PMOSFET $R_{DS(ON)}$				42		$\text{m}\Omega$
Low-Side NMOSFET $R_{DS(ON)}$				39		$\text{m}\Omega$
High-Side MOSFET Leakage Current	$I_{LX(\text{leak})}$	$V_{LX}=12\text{V}$ , $V_{OUT}=0\text{V}$			10	$\mu\text{A}$
Low-Side MOSFET Leakage Current		$V_{LX}=12\text{V}$			10	$\mu\text{A}$
Oscillation Frequency	$F_{osc}$		400	500	600	KHz
OUT Short-circuit Detection Threshold	$OUT_{(SC)}$	OUT voltage Falling		1.5		V
OUT Output Overvoltage Protection Threshold	$V_{OUT\_OVP}$	$V_{OUT}$ Rising		13.5		V
OUT OVP Hysteresis on Input Voltage	$V_{OUT\_HYS\_O\_VP}$	$V_{OUT}$ Falling		300		mV
OUT Short Circuit Fold-back Current Limit		$V_{IN}=3.3\text{V}$		100		mA
Low-side MOS Switch Current Limit		$V_{IN}=3.3\text{V}$		8		A
Line Regulation		$V_{IN}=3.2\text{V}$ to OUT, $I_{OUT}=1\text{A}$			1	%
Load Regulation		$I_{OUT}=0.1\text{A}$ to $3\text{A}$ , $OUT=5\text{V}$		5		%
Maximum Duty Cycle	$D_{MAX}$	$V_{IN}=3.3\text{V}$	85	90	95	%
Soft Start Time	$T_{SS}$			1	3	$\text{mS}$
<b>Others</b>						
EN High-Level Input Voltage	$V_{IH}$		1.5			V
EN Low-Level Input Voltage	$V_{IL}$				0.4	V
EN Pull Down Resistor	$R_{EN}$			1		$\text{M}\Omega$
Thermal Shutdown Temperature (Note 3)	$T_{SD}$			160		$^\circ\text{C}$
Thermal Shutdown Temperature Hysteresis				30		$^\circ\text{C}$
<b>USB Data Line Specifications (D+, D-)</b>						

Data Detect Voltage	V <sub>DAT(REF)</sub>		0.25	0.325	0.4	V
Output voltage selection reference	V <sub>SEL_REF</sub>		1.8	2.0	2.2	V
Data Lines Short-Circuit Delay	T <sub>DAT(SHORT)</sub>	V <sub>OUT</sub> ≥ 0.8 V		10	20	ms
D+ High Glitch Filter Time	T <sub>GLITCH(BC)-D</sub> + H		1000	1250	1500	ms
D- Low Glitch Filter Time	T <sub>GLITCH(BC)-D</sub> - L		1			ms
Output Voltage Glitch Filter Time	T <sub>GLITCH(V)</sub> CHANGE		20	40	60	ms
D- Pull-Down Resistance	R <sub>D-(DWN)</sub>			20		KΩ
D+ to D- resistance during DCP mode	R <sub>DCP_DAT</sub>			40		Ω

Note : Not production tested.

## Outline Information

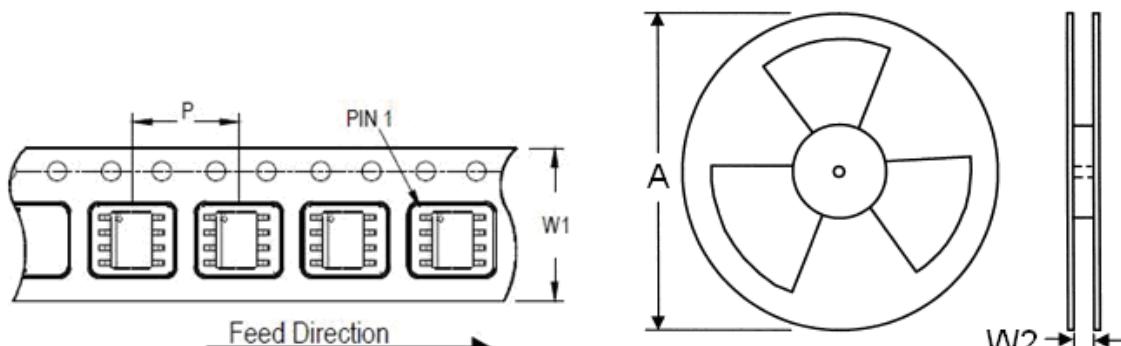
SOP-8 (Exposed Pad) Package (Unit: mm)



SYMBOLS UNIT	DIMENSION IN MILLIMETER	
	MIN	MAX
A	1.25	1.70
A1	0.00	0.15
A2	1.25	1.55
B	0.31	0.51
D	4.80	5.00
D1	3.04	3.50
E	3.80	4.00
E1	2.15	2.41
e	1.20	1.34
H	5.80	6.20
L	0.40	1.27

Note : Followed From JEDEC MO-012-E.

## Carrier Dimensions



Tape Size (W1) mm	Pocket Pitch (P) mm	Reel Size (A)		Reel Width (W2) mm	Empty Cavity Length mm	Units per Reel
		in	mm			
12	8	13	330	12.4	400~1000	2,500

### Life Support Policy

Fitipower's products are not authorized for use as critical components in life support devices or other medical systems.